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SERIAL NUMBER 10/681,583	FILING DATE 10/08/2003  RULE	CLASS 257	GROUP ART UNIT 2814	ATTORNEY DOCKET NO. CPAC 1029-5 D3
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## APPLICANTS

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## \*\* CONTINUING DATA \*\*\*\*\*

AC This appln claims benefit of 60/417,277 10/08/2002  
 and claims benefit of 60/460,541 04/04/2003  
 and is a CIP of 10/618,933 07/14/2003  
 which claims benefit of 60/460,541 04/04/2003

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

AC None

IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 01/02/2004

Foreign Priority claimed 35 USC 119 (a-d) conditions met	<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	STATE OR COUNTRY CA	SHEETS DRAWING 20	TOTAL CLAIMS 38	INDEPENDENT CLAIMS 2
Verified and Acknowledged	Examiner's Signature: <i>Atunns Charles</i> Initials:				

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## TITLE

Semiconductor multi-package module having inverted second package stacked over die-down flip-chip ball grid array (BGA) package

FILING FEE

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